



Final Product Change Notification

201909001F02

Issue Date: 27-Apr-2020

Effective Date: 26-Jul-2020

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.



QUALITY

Management Summary

SOT886 assembly and test will be transferred from ATGD and ATSN to ATBK. The transfer will assure supply continuity in the midst of the COVID-19 turmoil as well as improve package reliability.

Change Category

- | | | | | |
|--|--|---|--|---|
| <input type="checkbox"/> Wafer Fab Process | <input checked="" type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input checked="" type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input checked="" type="checkbox"/> Assembly Location | <input checked="" type="checkbox"/> Packing/Shipping/Labeling | <input checked="" type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

XSON6 (SOT886) Assembly/Test Transfer from ATGD and ATSN to ATBK

Description of Change

NXP Semiconductors is transferring assembly and test of the SOT886 (XSON6) package from ATSN and ATGD to ATBK. This will mitigate supply continuity concerns with ATSN (currently on lockdown) and ATGD during the COVID-19 crisis. There are no changes to the die and packing orientation. Standard ATBK materials and flows will be used including a roughened leadframe to improve package delamination performance. Please refer to the attached qualification report for detail. Product data sheets have been updated with new orderable part numbers to reflect the use of Static Shielding Bags (SSB). Although the planned first shipment is 90 days from notification, customer may request product delivery sooner and NXP will provide as available.

Reason for Change

Move production to an NXP facility to improve product quality and to assure product delivery especially during the COVID-19 crisis.

Identification of Affected Products

Packing Labels will show Product Manufacturing Code (PMC) "n" to reflect ATBK assembly.

Product Availability

Sample Information

Samples are available from 16-Sep-2019
Samples available per attached schedule.

Production

Shipment dates are product specific, see attached plan

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 27-May-2020.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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NXP Semiconductors

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Changed OPN	Changed 12NC	New Orderable Part#	New part 12NC
NX3L1G3157GM,115	935284122115	NX3L1G3157GMZ	935284122471